



SOCIETY OF INDO AMERICAN ENGINEERS AND ARCHITECTS

A not-for-profit professional organization

Committee 2023 - 2025

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(646) 522-7755

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(732) 290-5374

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AIA (201) 323-2290

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ASST. TREASURER

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IMM. PAST PRESIDENT

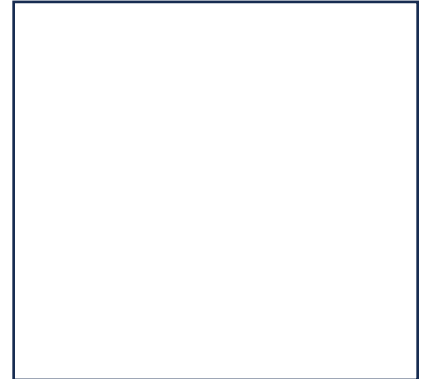
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SIAEA SCHOLARSHIP APPLICATION – 2023

BANSI SHAH MEMORIAL LOAN SCHOLARSHIP-2023



insert current photo here.

[I] Personal Information:

Full Name: _____

Permanent Address: _____

(Current address): _____

Phone No: (Home) _____ Cell#: _____

Place of Birth: _____ Date of Birth _____

E-mail address _____

Father's Name: _____

Father's Address (if different): _____

Father's Email _____ Phone no: _____

Father's Occupation: _____

[II] Educational Information:

Current study/Degree Course taken: _____ Class: _____

Current University's City and State: _____

Results / Grades:

Graduate / master's studies:

1st year _____

2nd Year _____

Undergraduate Studies:

4th year _____

3rd Year _____

2nd Year _____

1st Year _____



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III Financial Information:

Family's Annual Income (must submit the last 2 income tax returns): _____

SOURCES OF FINANCE:

Scholarship(s) received from other places	\$	_____
Loan(s) received from other places	\$	_____
Family Contribution.....	\$	_____
Assistantship (College).....	\$	_____
Miscellaneous other sources of help.....	\$	_____
Total -	\$	_____

EXPENSES:

Tuition/year: _____ Books: _____ Lodging & Boarding: _____

State your financial needs in view of your expenses, family's income, and other financial sources:

IV. General Information

Extra-Curricular Activities (Games/Cultural/Social etc.):

Define your objectives and goals during and after your study is over: (You can attach a separate sheet)

V SIAEA Membership:

(i) Are you a SIAEA member? YES___ No___ *If yes, since when*___ & *your membership #:* _____

(ii) *If not, please apply online for **Student Membership** as soon as possible, as you must be a member in order to receive this scholarship. (A \$30 application fee will be required if you are not a current SIAEA member.)*



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VI References (See 'Statement from Reference' attached herewith)

Please provide two references of the people who know you well and are prepared to sign the attached.
'Statement from Reference'

Name: _____

Address: _____

Phone number: _____ Email address _____

Name: _____

Address: _____

Phone number: _____ Email address _____

The information furnished above is true to the best of my knowledge and belief and I hereby agree to abide by the terms and conditions of the scholarship. I solemnly declare that I am a student from Indian Origin and if I am awarded this scholarship, I will repay it within two years from the date of my graduation. I may be charged interest at the then prevailing rate on the loan balance if I fail to do so.

Applicant's Signature: _____ Date _____

Print Name: _____



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Statement from Reference -1

SOCIETY OF INDO AMERICAN ENGINEERS AND ARCHITECTS

180 Lexington Ave, 2nd Floor.

Passaic, NJ 07055

Dear Sirs,

I, the undersigned, agree to keep in touch with the applicant and provide his/her latest address and phone number to SIAEA. if requested.

I understand that it would be my moral responsibility to persuade the applicant to refund the loan as quickly as possible, so that the SIAEA can recycle the funds to help other bright and needy students.

Sincerely,

(Signature)

Print Name: _____

Address: _____

Phone # (Office): _____

Phone # (Home): _____

Fax #: _____

E-mail Address: _____

Date: _____

.



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Statement from Reference -2

SOCIETY OF INDO AMERICAN ENGINEERS AND ARCHITECTS

180 Lexington Ave, 2nd Floor.

Passaic, NJ 07055

Dear Sirs,

I, the undersigned, agree to keep in touch with the applicant and provide his/her latest address and phone number to SIAEA. if requested.

I understand that it would be my moral responsibility to persuade the applicant to refund the loan as quickly as possible, so that the SIAEA can recycle the funds to help other bright and needy students.

Sincerely,

(Signature)

Print Name: _____

Address: _____

Phone # (Office): _____

Phone # (Home): _____

Fax #: _____

E-mail Address: _____

Date: _____



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Parents' Consent

Statement from Parents/Guardian

Dear Sir,

I understand that as a father/mother/guardian it would be my moral responsibility to persuade my son/daughter (the applicant) to refund the loan as quickly as possible, so that the SIAEA can recycle the funds to help other bright and needy students. The purpose of this loan(s) is only you can avoid the higher interest rates of the industry and momentarily could get the financial help.

The information furnished along with the scholarship application is true to the best of my knowledge and belief and I hereby agree to abide by all the terms and conditions of the scholarship and promissory note if my son/daughter awarded this scholarship, I will make sure he/she repay it within two years from the date of his/her graduation.

FOR VALUE RECEIVED as Loan Scholarship I undersigned _____ promises to pay to the SOCIETY OF INDO AMERICAN ENGINEERS AND ARCHITECTS in the event if my child fail to repay the loan amount within the time given by SIAEA- at the address of Treasurer or Scholarship trustees-SIAEA (current address – 180 Lexington Ave, 2nd Floor, Passaic, NJ 07055) or at the office address of the SIAEA as mentioned above, OR at may be given to the most current address in SIAEA Website at the time of repaying the loan scholarship.

I agree to keep SIAEA scholarship trustees always informed of whereabouts of my son/daughter. I also understand and agree with the terms and conditions of this Loan Scholarship awarded to my son/daughter.

My Current Residential Address (India) is as below:

Name:

Present (USA or India) Address:

City/State/PIN:

E-Mail Address:

Phone No.:

IN WITNESS WHEREOF _____ has affixed his signature in my presence

On this _____ day of _____, 20____ Witness: _____

Applicant's Father/ Mother / Guardian's Signature: _____ Date _____

Print Name: _____



SOCIETY OF INDO AMERICAN ENGINEERS AND ARCHITECTS

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PROMISSORY NOTE:

Borrower (Recipient of Scholarship): _____

Lender: **SOCIETY OF INDO AMERICAN ENGINEERS AND ARCHITECTS**

Amount: \$ 3000.00 to up to \$ 5,000.00 (Three Thousand US Dollars to up to five thousand dollar) OR identify the amount _____ FOR VALUE RECEIVED as Loan Scholarship I undersigned _____ promises to pay to **SOCIETY OF INDO AMERICAN ENGINEERS AND ARCHITECTS, 180 Lexington Ave, 2nd Floor, Passaic, NJ 07055** at the address of Treasurer / Scholarship trustees-SIAEA as may be given in application form at the time of repaying the loan scholarship, the principal sum of _____ (\$ 3000.00 to \$ 5,000.00 OR identify the amount _____) without any interest within two years of completion of my study.

I _____ agrees to keep SOCIETY OF INDO AMERICAN ENGINEERS AND ARCHITECTS always informed of my whereabouts. I will send a progress report of my study every six (6) months. I also understand and agree with the terms and conditions of this Loan Scholarship.

At any time while not in default under this note, I may be allowed to pay the outstanding balance then owing under this note in full to SIAEA without any bonus or penalty. Notwithstanding anything to the contrary in this Note, if I default in performance of any obligation under this Note, then SIAEA may declare that principal amount owing under this Note at that time immediately to be due and payable. I also understand and agree that interest and other applicable fees will be payable by me in case of default and after 2 years period. My Current Residential Address (USA/Abroad and India addresses) are as below:

Name:

Present (USA/Abroad) Address:
City/State/ZIP:

E-Mail Address: _____ Phone No.: _____

IN WITNESS WHEREOF _____ has affixed his signature in my presence

On this _____ day of _____, 200

Borrower (Recipient of Scholarship)

Signed under OATH

Notary Public – Seal

Applicant's Permanent Address in USA and INDIA's address (include Father's name):
Address:

E-Mail Address: _____ Phone No.: _____

Permanent Address for one of your two USA References:
Name:
Address:
City/State/ZIP:
E-Mail Address: _____

Phone No.: _____



RULES, GENERAL INFORMATION, AND INSTRUCTIONS FOR BANSI SHAH LOAN SCHOLARSHIP APPLICATION FROM TO SIAEA

1. This program entails awarding a one-time scholarship / loan scholarship of up to \$ 5000.00 to bright and needy students of Indian origin (pursuing undergraduate or graduate study in USA) for further studies to help them tide over initial financial problems on start up. This is an interest free loan scholarship and released on the student's signing a notarized Promissory note and agreeing to keep SIAEA informed of his whereabouts, changes in addresses, phone numbers etc. and to repay the loan amount within two years or earlier after completion of the studies. The application deadline and award notification deadline dates are as under:

Application Deadline date: to be post mailed No later than September 23, 2023; emailed by 5.00pm 09/26/2023.

Award Notification date: September 30, 2023

2. The applicant should carefully follow the following instructions while submitting the application:

Para 1: Address of the Applicant:

The applicant's address on the application form should be permanent USA / India address as well as address of country admission secured (abroad) where the applicant is finally staying, and mail can be sent to. The applicant is supposed to be secured admission and valid visa in USA to get qualified for the loan. The check of the loan amount will be remitted to the name of the school / university where applicant is studying or enrolled to study. **Applications missing any information requested or finding incorrect information will not be considered.**

Para 2: Educational Information:

Transcripts: Attach Transcripts from the College/ University for the last Degree course.

If applicant is on student visa, A copy of I-20 Form from the College/university, the applicant is attending is required to accompany the application. A copy of admission letter from the college/University the student is going to attend is also required. Transcripts of the previous year result

Para 3: Financial Information:

Copies of last two Income Tax returns from Parents (Father & mother if filing separate or both if filing joint) are required to support family income is stated on the application form. Copies should be on standard 8.5" x 11." size papers.

Para 4: General Information:

Describe briefly Extra Curricular activities related to social, educational, and cultural activities especially regarding community uplifting programs.

Para 5: References:

Statements from references from relatives should be attached with the application and mail together.

The application with incomplete information and / or attachments are likely to result in delayed processing or not getting considered.



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Para 6: Contact Information:

Mr. Ketan Shah, (Scholarship Chair), Mitul Patel (President elect), Yogesh Mistry (Secretary) or Nihal Shah (Scholarship committee & Board of director), Seema Malik (Scholarship Committee and Board member)
SOCIETY OF INDO AMERICAN ENGINEERS AND ARCHITECTS
180 Lexington Ave, 2nd Floor.
Passaic, NJ 07055

Para 7: Parents' Consent:

Statements from Parents/Guardian will be required only after you receive award notification (Not at the time of application)

Para 8: Promissory Note:

Recipient of loan scholarship is required to sign a promissory note in front of Notary Public with Notary Public's signature and seal.

Promissory Note will be required only after you receive award notification (not at the time of application)

Para 9: Applicant must be SIAEA member:

You can become a student member (\$ 30.00) or life member (\$ 250.00) by applying membership online www.siaeany.org. To be eligible to get the scholarship, one has to be a SIAEA member.

Check will be released upon return of original promissory note to:

Mr. Ketan Shah, (Scholarship Chair)
SOCIETY OF INDO AMERICAN ENGINEERS AND ARCHITECTS
180 Lexington Ave, 2nd Floor.
Passaic, NJ 07055 Email –

president@siaeany.org

secretary@siaeany.org

Ketan Shah: ketan.icc@gmail.com

Nihal Shah: Nihal.shah@iccincorporated.com

Mitul Patel: mpatel@keriengineering.com

Yogesh Mistry: ym@mistrydesignllc.com

Seema Malik: seema.malik@tastement.com

Upon completion of studies, the loan should be repaid within two years.

Make check payable to **SOCIETY OF INDO AMERICAN ENGINEERS AND ARCHITECTS** and mail check to Treasurer at above or SIAEA current address.